MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS
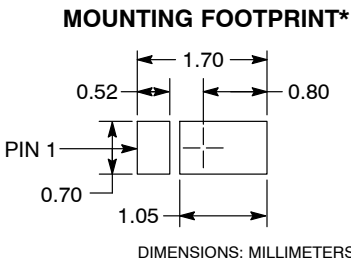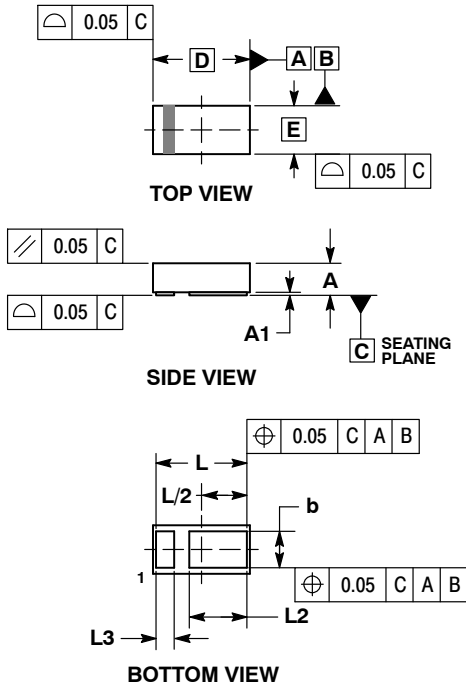
ON Semiconductor®

DSN2, 1.6x0.8, 0.9P, (0603)
CASE 152AB
ISSUE C

DATE 30 APR 2017

SCALE 8:1

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.25	0.31
A1	---	0.05
b	0.55	0.65
D	1.60 BSC	
E	0.80 BSC	
L	1.45	1.55
L2	0.90	1.00
L3	0.25	0.35

TOP VIEW

0.05 C

D A B

E

0.05 C

SIDE VIEW

0.05 C

0.05 C

A

A1

C SEATING PLANE

BOTTOM VIEW

0.05 C A B

L

L/2

b

1

0.05 C A B

L2

L3

GENERIC MARKING DIAGRAM1*
PIN 1

XXXX
YYY

XXXX = Specific Device Code
YYY = Year Code

GENERIC MARKING DIAGRAM2*
PIN 1

XXM

XX = Specific Device Code
M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, "G", may or not be present. Some products may not follow the Generic Marking.

CATHODE BAND MONTH CODING

DEC NOV OCT
SEP
JUN
MAR
FEB
JAN

XXXX DEVICE CODE
YYY YEAR CODE

XXXX
Y09 (EXAMPLE)

INDICATES AUG 2009

MOUNTING FOOTPRINT*

1.70
0.52
0.80
PIN 1
0.70
1.05

DIMENSIONS: MILLIMETERS
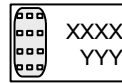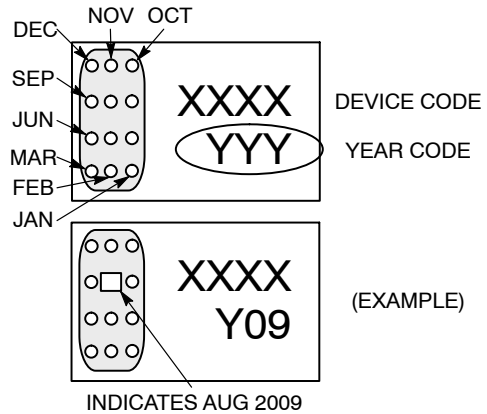
See Application Note AND8464/D for more mounting details

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER:	98AON40452E	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.	
DESCRIPTION:	DSN2, 1.6X0.8, 0.9P, (0603)		PAGE 1 OF 1